



SOT1188-1

plastic, single in-line package

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---------------------------|
| Terminal position code | S (single) |
| Package type descriptive code | SIL4 |
| Package type industry code | SIL4 |
| Package style descriptive code | BCC (bottom chip carrier) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| IEC package outline code | --- |
| JEDEC package outline code | --- |
| JEITA package outline code | --- |
| Mounting method type | T (through-hole mount) |
| Issue date | 4-10-2010 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|------|-------|------|
| D | package length | 10.85 | - | 11 | 11.15 | mm |
| E | package width | 7.3 | - | 7.4 | 7.5 | mm |
| A | seated height | 1.85 | - | 1.95 | 2.05 | mm |
| e | nominal pitch | - | - | 1.8 | - | mm |
| n ₂ | actual quantity of termination | - | - | 4 | - | |



2. Package outline

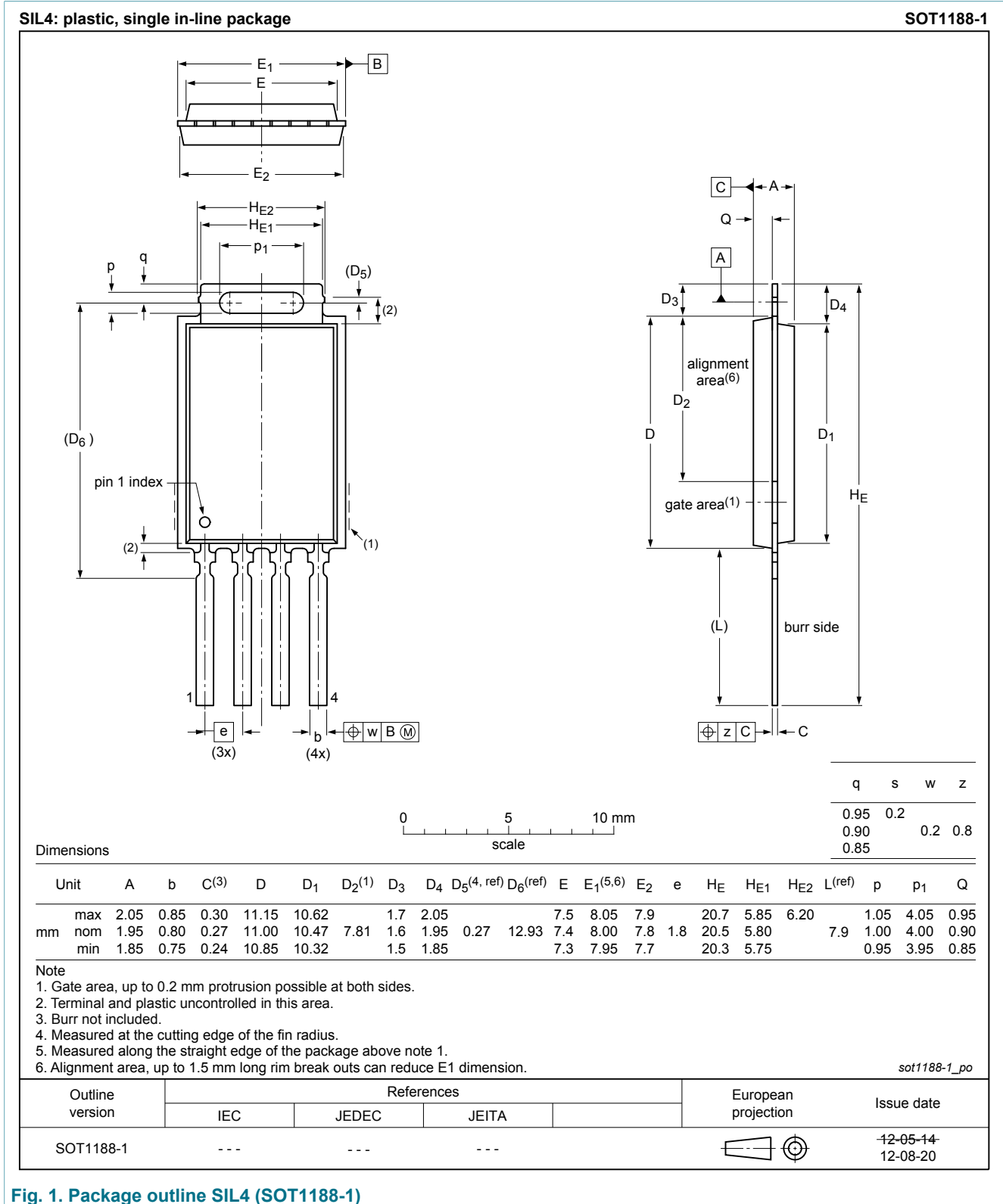


Fig. 1. Package outline SIL4 (SOT1188-1)

3. Legal information

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